

Serial No.10/769,127
HP Docket No: 200209576-1

REMARKS

This communication is in response to the Office Action dated January 26, 2006. Claims 1-10, 13-20, 22 and 23 are pending in the present Application.

Claims 11, 12, 21 and 24-30 have been withdrawn from consideration. Claims 1-10, 13-20, 22 and 23 are rejected.

§102 Rejections

Claims 1-10, 13-20, 22 and 23

For ease of review, Applicant reproduces independent claims 1 and 13 herein below:

1. A method for forming a semiconductor device comprising:
forming a 3-dimensional (3D) pattern in a substrate; and
depositing at least one material over the substrate in accordance with
desired characteristics of the semiconductor device.
13. A system for forming a semiconductor device comprising:
means for forming a 3-dimensional (3D) pattern in a substrate; and